

/ Descriptions

SOD-323 4 5 5 6 7 8 3 9 : ; <`
Schottky Diode in a SOD-323 Plastic Package.

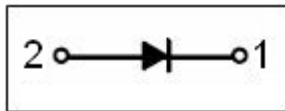
/ Features

= > ? @ A B = @ C D B E : F G H B = I J K L B M N O P <`
Q S TR U S V W X R Q V Z [` W R \ B +RS] R Q V Z [` ^ [_ Y T _ V Y Ra B t X [U c [` d R Q U Y e d U R Y [_ Y Ra B +RS ` d R S [U
f Racgh \ Y Ra ` % \ Q _ V Y Ra c B i j ` d U R W g _ Y k

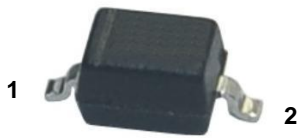
/ Applications

7 8 3 9 : ; k<`
l _ n R Y n e ` W R W [k

/ Equivalent Circuit

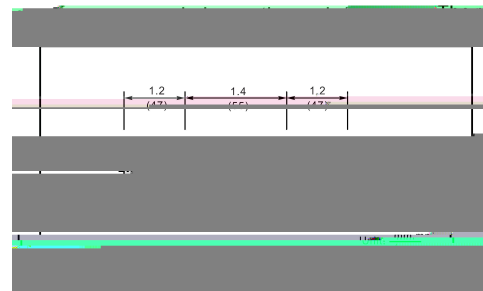


/ Pinning



PIN1:Cathode

PIN2:Anode



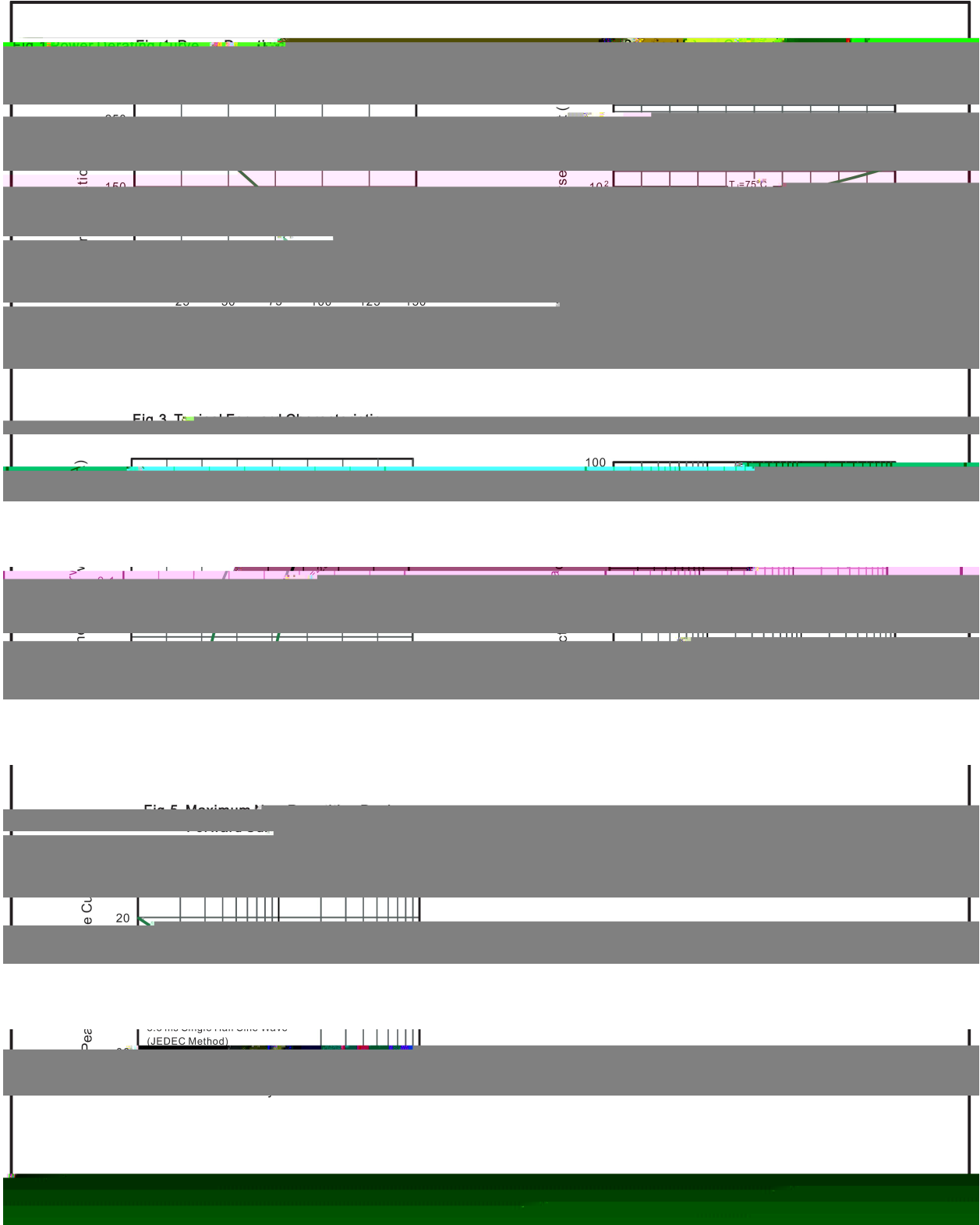
/ Marking

Model	B1040WS
Marking	HSZ

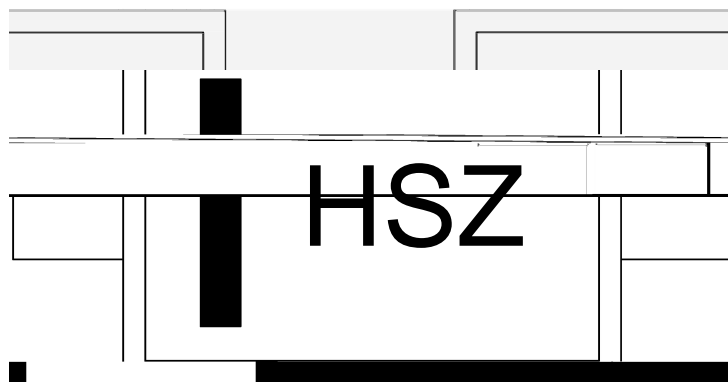
B1040WS



/ Electrical Characteristic Curve



/ Marking Instructions



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i | ' } ~ € , fl'
l f_n ' } ...r , fl'

Note:

H: Company Code.

l f_n ' dURVg_Yte\k

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



- | | | | | | | |
|---|-----|-----|----|----------|-------|---|
| 1 | 150 | 180 | 60 | 90sec; | Note: | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260 5 Time:10 1 sec

/ Packaging SPEC.

/ REEL

Package Type 封	Units		Units			Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box